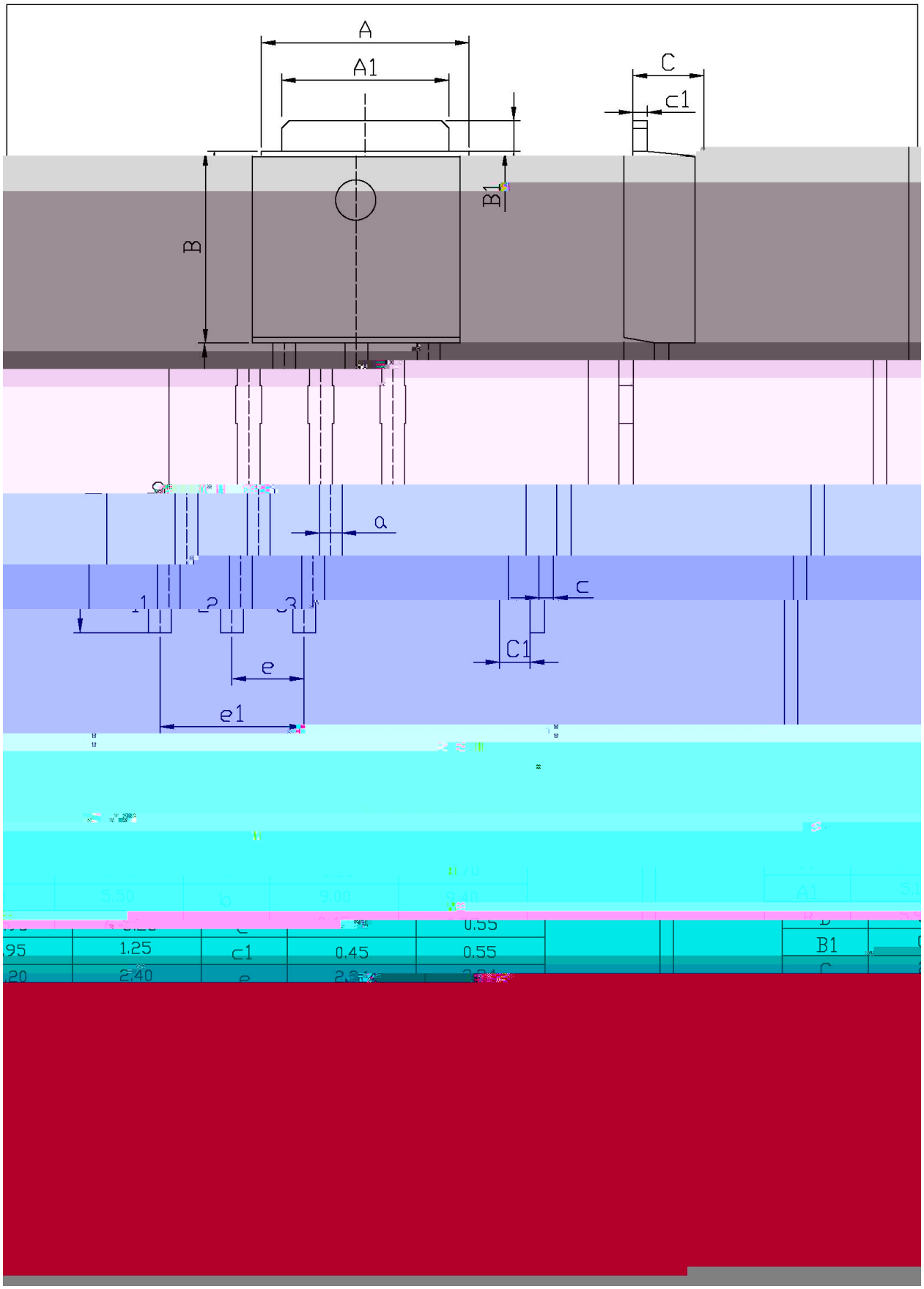
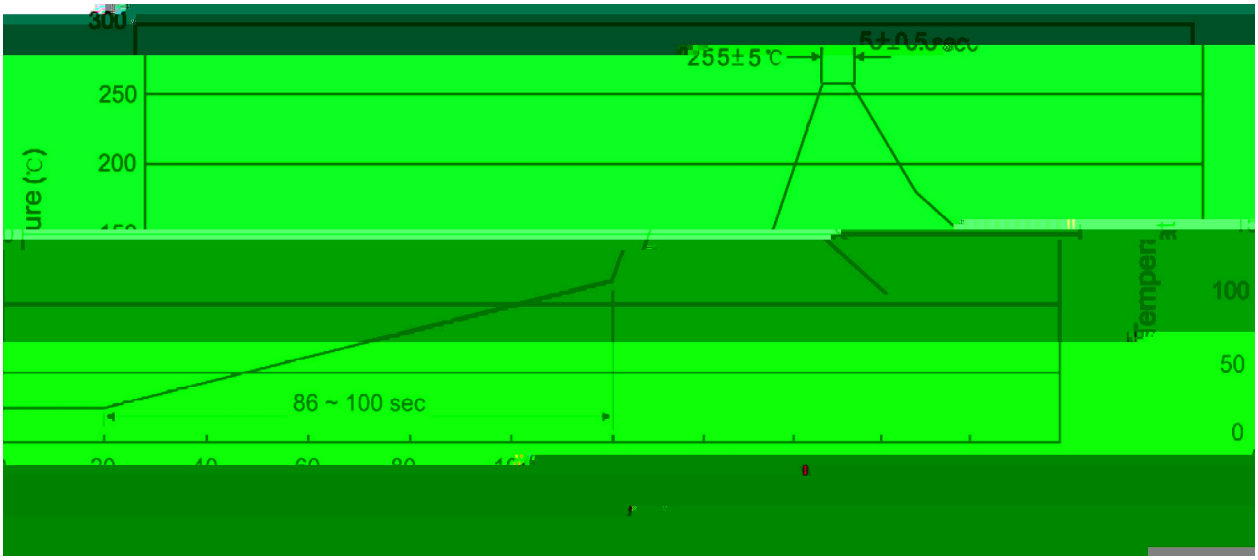
TO-251 ṂṂ Ḷ N

v ̈Ω Parameter	ϒ N Symbol	̈ΩΘ̈ Rating	D Ĥ Unit
Drain-Source Voltage	V_{DSS}	700	V
Drain Current	I_D(Tc=25)	6.0	A
Drain Current	I(	T	5

/ Package Dimensions



( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 ĺ ♬ □ ỷ 25 Ḱ 150 ɬ ı `H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 255 ° 5 ɬ ı `H ڑ ˋY ⺈ ⺮ 5 ° 0.5sec;

3 ì ˙ ⺈ ˛ ɔ ھ ỷ ⺮ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:255 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ɬ `H ڑ χ 10 ° 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

ˋΩ̣ τ̣ γ ⊢ / BULK

Package Type	Units					Dimension (unit mm^3)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-251	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195

ˇ ˥ γ ⊢ / TUBE

Package Type	Units	Dimension (unit mm^3)
	Units/Tube /	